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## **Quarterly Reliability Monitoring Results**

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier  |  | User Part Number   |                       |           |            |           |  |  |
|---|--|--|-----------------------|-----------|------------|-----------|--|--|
| Nexperia B.V.                                   |  | BAS70VY  |                       |           |            |           |  |  |
| Name of Laboratory<br>Assembly reliability labs |  | Part Description   |                       |           |            |           |  |  |
|   |  | Nexperia DHAM  | Schottky              |           |            |           |  |  |
|   |  | SMD package  |                       |           |            |           |  |  |
| Test  |  | Test Conditions  | Duration              | # Lots    | # Quantity | # Rejects |  |  |
|   | TEST   |  |                       |           |            |           |  |  |
|   | Pre- and Post-Stress   |  |                       |           |            |           |  |  |
| # 1   | Electrical Test  | Tamb = 25 °C   | N/A                   | see below | all parts  | see below |  |  |
|   | PC   | JESD22-A113<br>Bake Tamb = 125 °C<br>Soak Tamb = 85 °C, RH = 85%   | 24 hours<br>168 hours |           |            |           |  |  |
| # 2   | Preconditioning  | Reflow soldering   | 3 cycles              | 1514      | 64430      | 0         |  |  |
| # 5   | <b>HTRB</b><br>High Temperature Reverse<br>Bias                | $ \begin{split} \text{MIL-STD-750-1} \\ \text{M1038 Method A} \\ \text{Tj} = \text{Tjmax}, \text{Vr} = 100\% \text{ of max. datasheet} \\ \text{reverse voltage}^{[1]} \end{split} $ | 1000 hours            | 206       | 9320       | 0         |  |  |
| " 5   |  |  | 1000 110015           | 200       | 5520       | 0         |  |  |
| # 7   | <b>TC</b><br>Temperature Cycling                               | JESD22-A104<br>-65 °C to Tjmax, not to exceed 150°C  | 500 cycles            | 311       | 14080      | 0         |  |  |
| # 8 <b>or</b>                                   | <b>UHAST</b><br>Unbiased HAST                                  | JESD22-A118<br>Tamb = 130 °C, RH = 85 %  | — 96 hours            | 311       | 14080      | 0         |  |  |
| # 8a  | <b>AC</b><br>Autoclave   | JESD22-A102<br>Tamb = 121 °C, RH = 100 %<br>Pressure = 205 kPa (29.7 psia)   |                       |           |            |           |  |  |
| # 9   | <b>H3TRB</b><br>High Humidity High<br>Temperature Reverse Bias | JESD22-A101<br>Tamb = 85 °C, RH = 85%, VR = 80 % of<br>rated reverse voltage <sup>[1], [2]</sup>   | 1000 hours            | 311       | 14080      | 0         |  |  |
| # 10  | <b>IOL</b><br>Intermittent Operating Life                      | MIL-STD-750 Method 1037<br>ton = toff, devices powered to insure $\Delta Tj$ = 100 °C  | 333 hours             | 312       | 14120      | 0         |  |  |
|   |  |  |                       |           |            |           |  |  |
| # 20  | <b>RSH</b><br>Resistance to Solder Heat                        | JESD22-A111<br>260 °C ± 5 °C   | 10 s                  | 269       | 8070       | 0         |  |  |
| # 21  | <b>SD</b><br>Solderability                                     | J-STD-002  |                       | 222       | 6660       | 0         |  |  |

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab T | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-------------|------------|----------|---------|--------------------|------------|
| Nexperia    |            |          |         |                    |            |
| DHAM S      | Schottky   | 9320     | 0       | 0,46               | 2,19E+09   |

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